



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2016-09-01</b>
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>Floriana San Biagio</b>	<b>Representative Title</b>	<b>AMG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	A68C*UF08AJ6	A	MU1A	2016-09-01
Amount	UoM	Unit type	ST ECOPACK Grade	
1929.67	mg	Each	ECOPACK® 1	
	Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	15.9x11.x3.5	36	gull wing	
Comment	Package: 8C PowerSO 36 .430 BODY WIDTH; MDF valdi L6208PD			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	A68C*UF08A16					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	14.750	mg	supplier	die	Silicon (Si)	7440-21-3		14.193	mg	962237	7355
				supplier	metallization	Aluminium (Al)	7429-90-5		0.108	mg	7322	56
				supplier	metallization	Copper (Cu)	7440-50-8		0.002	mg	136	1
				supplier	metallization	Titanium (Ti)	7440-32-6		0.012	mg	814	6
				supplier	Passivation	Silicon Nitride	12033-89-5		0.032	mg	2169	17
				supplier	Passivation	Silicon Oxide	7631-86-9		0.185	mg	12542	96
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.008	mg	542	4
				supplier	back side metallization	Gold (Au)	7440-57-5		0.022	mg	1492	11
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.072	mg	4881	37
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.116	mg	7864	60
Leadframe	Copper & its alloys	1247.708	mg	supplier	alloy	Copper (Cu)	7440-50-8		1232.966	mg	988185	638952
				supplier	alloy	Iron (Fe)	7439-89-6		0.568	mg	455	294
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		1.037	mg	831	537
				supplier	metallization	Silver (Ag)	7440-22-4		13.137	mg	10529	6808
Soft solder	Other inorganic materials	10.250	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	9.993	mg	974927	5179
				supplier	solder	Silver (Ag)	7440-22-4		0.154	mg	15024	80
				supplier	solder	Tin (Sn)	7440-31-5		0.103	mg	10049	53
Bonding wires	Precious metals	1.733	mg	supplier	wire	Gold (Au)	7440-57-5		1.733	mg	1000000	898
				supplier	mold compound	Silica, vitreous	60676-86-0		517.479	mg	796999	268170
Encapsulation	Other Organic Materials	649.284	mg	supplier	mold compound	Biphenyl epoxy resin	85954-11-6		51.943	mg	80000	26918
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		16.232	mg	25000	8412
				supplier	mold compound	Phenol resin	9003-35-4		38.957	mg	60000	20188
				supplier	mold compound	Antimony Trioxide	1309-64-4		9.739	mg	15000	5047
				JIG - I	mold compound	Brominated Epoxy Resin	68541-56-0		12.986	mg	20000	6730
				supplier	mold compound	Carbon black	1333-86-4		1.948	mg	3000	1009
connections coating	Solder	5.946	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.946	mg	1000000	3081